

ABSTRACT

PHENOLIC RESIN MOLDING MATERIAL

The present invention provides a phenolic resin molding material comprising:

a phenolic resin composition comprising 100 parts by weight of a phenolic resin, 10-70 parts by weight of an organic filler and 10-70 parts by weight of an inorganic filler, and

a releasant consisting of 0.2-4 parts by weight of an amide wax having a melting point of 130-150°C and 0.1-2 parts by weight of an ester wax and/or a partially saponified ester wax each having a melting point of 80-105°C.

This phenolic resin molding material can provide a molded article which has good releasability and which shows excellent adherence to coating film formed thereon and excellent surface smoothness even after treatment at a high temperature and a high humidity.